Lattice Semiconductor Corporation - LFECP6E-3QN208I Datasheet

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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	147
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfecp6e-3qn208i

LatticeECP/EC Family Data Sheet Introduction

September 2012 **Data Sheet**

Features

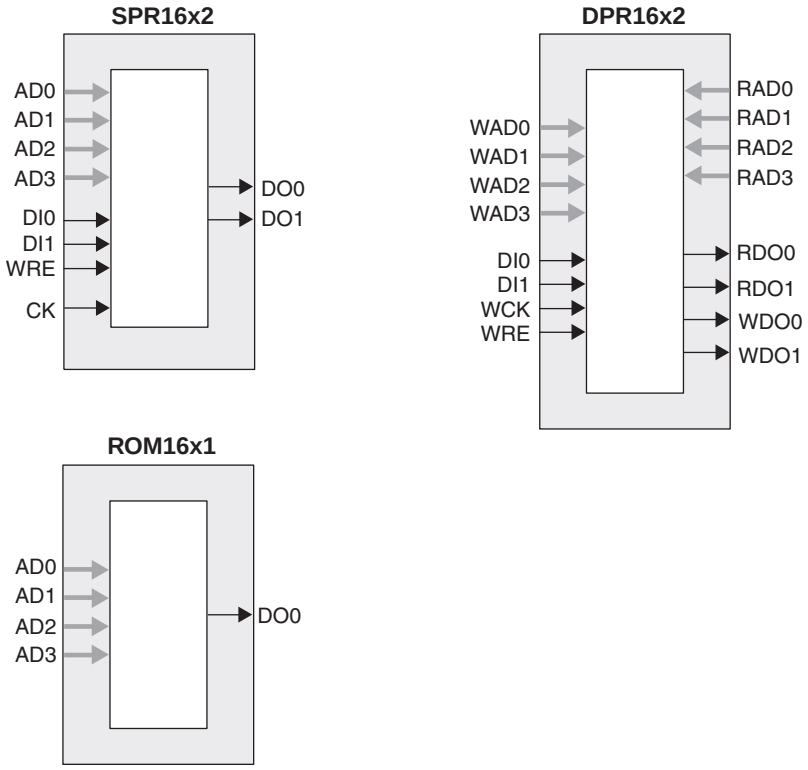
- **Extensive Density and Package Options**
  - 1.5K to 32.8K LUT4s
  - 65 to 496 I/Os
  - Density migration supported
- **sysDSP™ Block (LatticeECP™ Versions)**
  - High performance multiply and accumulate
  - 4 to 8 blocks
    - 4 to 8 36x36 multipliers or
    - 16 to 32 18x18 multipliers or
    - 32 to 64 9x9 multipliers
- **Embedded and Distributed Memory**
  - 18 Kbits to 498 Kbits sysMEM™ Embedded Block RAM (EBR)
  - Up to 131 Kbits distributed RAM
  - Flexible memory resources:
    - Distributed and block memory
- **Flexible I/O Buffer**
  - Programmable sysI/O™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - SSTL 3/2 Class I, II, SSTL18 Class I
    - HSTL 18 Class I, II, III, HSTL15 Class I, III
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **Dedicated DDR Memory Support**
  - Implements interface up to DDR400 (200MHz)
- **sysCLOCK™ PLLs**
  - Up to four analog PLLs per device
  - Clock multiply, divide and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
  - SPI boot flash interface
  - 1.2V power supply
- **Low Cost FPGA**
  - Features optimized for mainstream applications
  - Low cost TQFP and PQFP packaging

Table 1-1. LatticeECP/EC Family Selection Guide

Device	LFEC1	LFEC3	LFEC6/ LFECP6	LFEC10/ LFECP10	LFEC15/ LFECP15	LFEC20/ LFECP20	LFEC33/ LFECP33
PFU/PFF Rows	12	16	24	32	40	44	64
PFU/PFF Columns	16	24	32	40	48	56	64
PFUs/PFFs	192	384	768	1280	1920	2464	4096
LUTs (K)	1.5	3.1	6.1	10.2	15.4	19.7	32.8
Distributed RAM (Kbits)	6	12	25	41	61	79	131
EBR SRAM (Kbits)	18	55	92	276	350	424	498
EBR SRAM Blocks	2	6	10	30	38	46	54
sysDSP Blocks[1]	—	—	4	5	6	7	8
18x18 Multipliers[1]	—	—	16	20	24	28	32
V_{CC} Voltage (V)	1.2	1.2	1.2	1.2	1.2	1.2	1.2
Number of PLLs	2	2	2	4	4	4	4
Packages and I/O Combinations:							
100-pin TQFP (14 x 14 mm)	67	67					
144-pin TQFP (20 x 20 mm)	97	97	97				
208-pin PQFP (28 x 28 mm)	112	145	147	147			
256-ball fpBGA (17 x 17 mm)		160	195	195	195		
484-ball fpBGA (23 x 23 mm)			224	288	352	360	360
672-ball fpBGA (27 x 27 mm)						400	496

1. LatticeECP devices only.

Figure 2-5. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM[1]	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x 2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

1. These modes are not available in PFF blocks

Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from CLKOP (PLL internal), from clock net (CLKOP) or from a user clock (PIN or logic)
RST	I	"1" to reset PLL
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lead, "0": Lag
DDAIDEL[2:0]	I	Dynamic Delay Input
DDAOZR	O	Dynamic Delay Zero Output
DDAOLAG	O	Dynamic Delay Lag/Lead Output
DDAODEL[2:0]	O	Dynamic Delay Output

For more information about the PLL, please see the list of technical documentation at the end of this data sheet.

Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved regardless of where the select signal is toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-13 illustrates the DCS Block Macro.

Figure 2-13. DCS Block Primitive

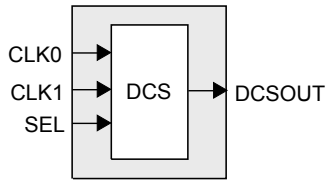
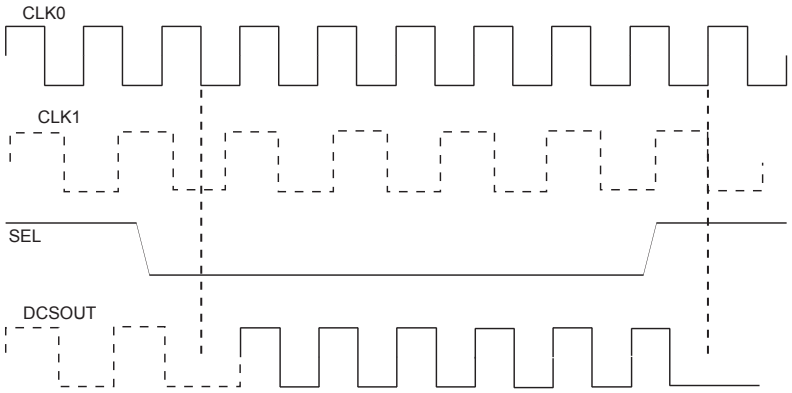


Figure 2-14 shows timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information about the DCS, please see the list of technical documentation at the end of this data sheet.

Figure 2-14. DCS Waveforms



sysMEM Memory

The LatticeECP/EC devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Table 2-7. Maximum Number of Elements in a Block

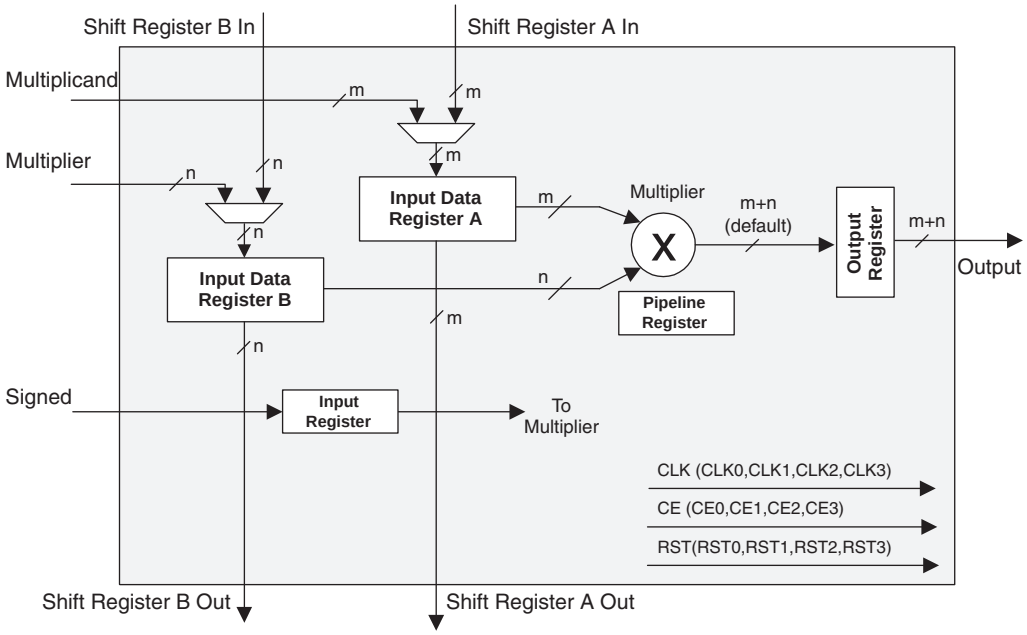
Width of Multiply	x9	x18	x36
MULT	8	4	1
MAC	2	2	—
MULTADD	4	2	—
MULTADDSUM	2	1	—

Some options are available in four elements. The input register in all the elements can be directly loaded or can be loaded as shift registers from previous operand registers. In addition by selecting “dynamic operation” in the ‘Signed/Unsigned’ options the operands can be switched between signed and unsigned on every cycle. Similarly by selecting ‘Dynamic operation’ in the ‘Add/Sub’ option the Accumulator can be switched between addition and subtraction on every cycle.

MULT sysDSP Element

This multiplier element implements a multiply with no addition or accumulator nodes. The two operands, A and B, are multiplied and the result is available at the output. The user can enable the input/output and pipeline registers. Figure 2-19 shows the MULT sysDSP element.

Figure 2-19. MULT sysDSP Element



MAC sysDSP Element

In this case the two operands, A and B, are multiplied and the result is added with the previous accumulated value. This accumulated value is available at the output. The user can enable the input and pipeline registers but the output register is always enabled. The output register is used to store the accumulated value. A registered overflow signal is also available. The overflow conditions are provided later in this document. Figure 2-20 shows the MAC sysDSP element.

Input Register Block

The input register block contains delay elements and registers that can be used to condition signals before they are passed to the device core. Figure 2-26 shows the diagram of the input register block.

Input signals are fed from the sysI/O buffer to the input register block (as signal DI). If desired the input signal can bypass the register and delay elements and be used directly as a combinatorial signal (INDD), a clock (INCK) and in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, reduces input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-27 shows the input register waveforms for DDR operation and Figure 2-28 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to system clock domain. For further discussion on this topic, see the DDR Memory section of this data sheet.

Figure 2-26. Input Register Diagram

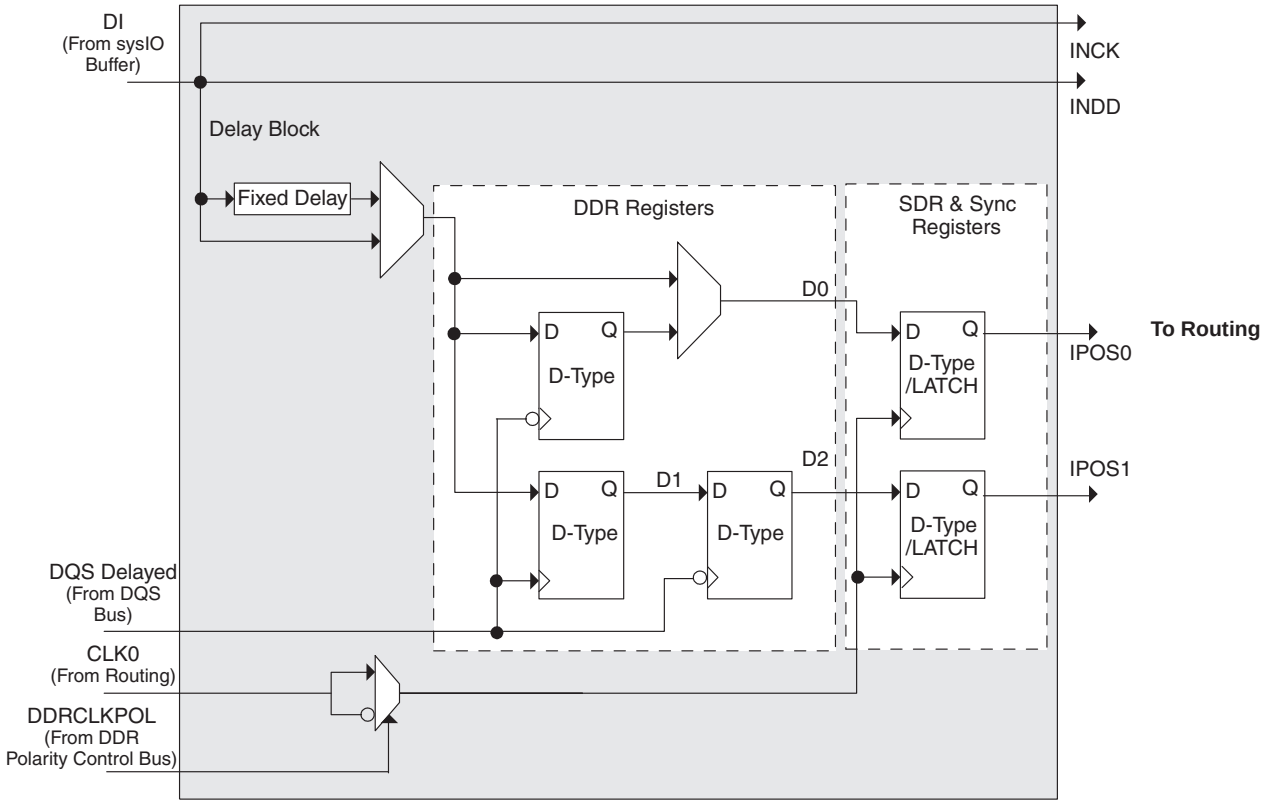


Figure 2-27. Input Register DDR Waveforms

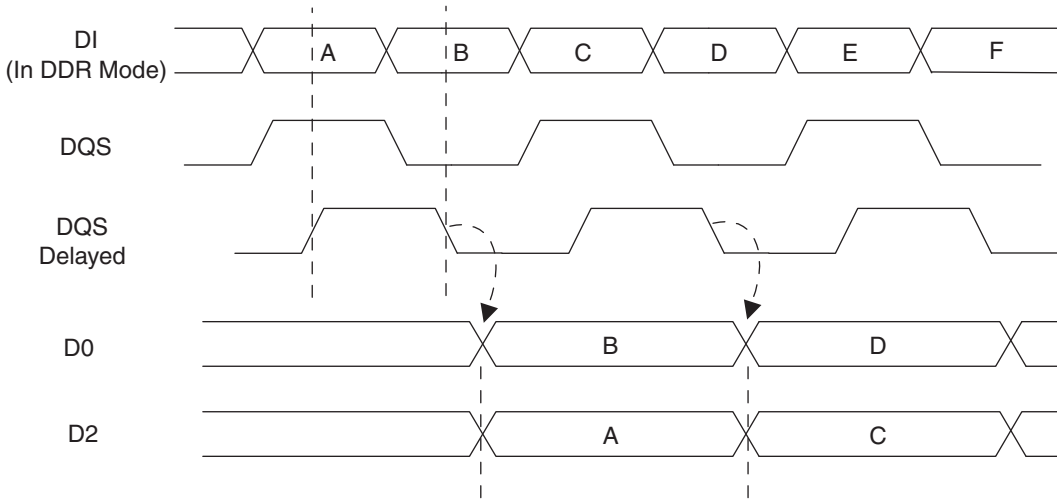
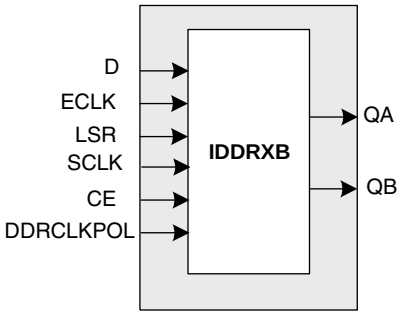


Figure 2-28. INDDRXB Primitive



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysI/O buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-29 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-30 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Figure 2-32. DQS Local Bus.

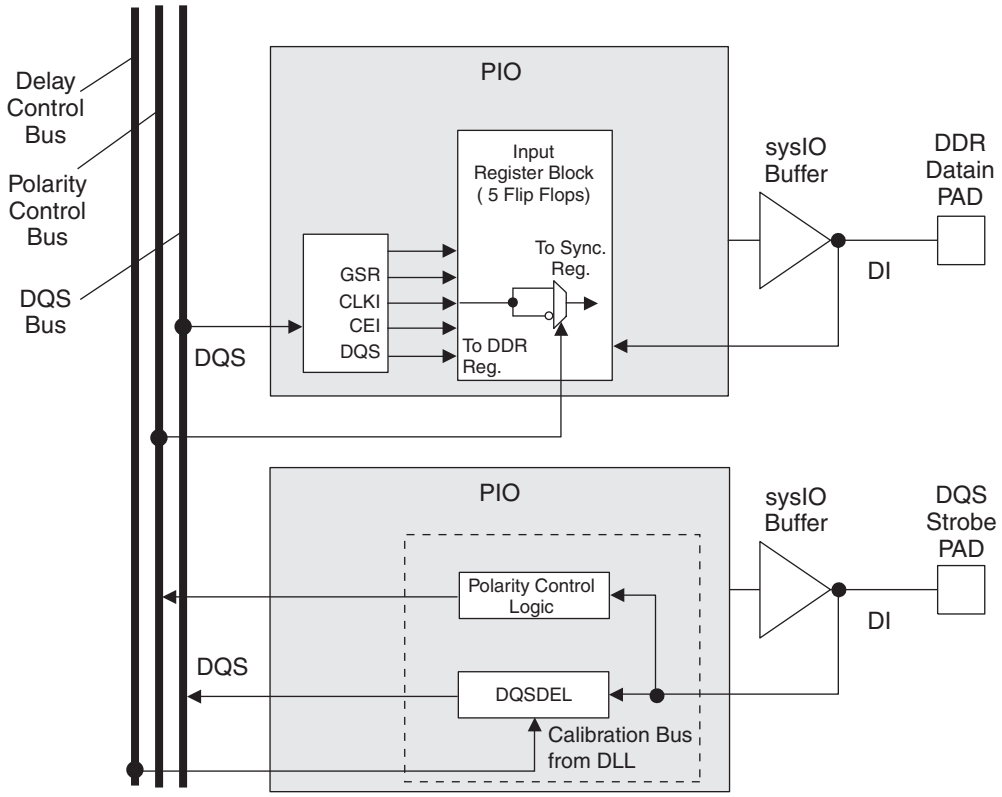
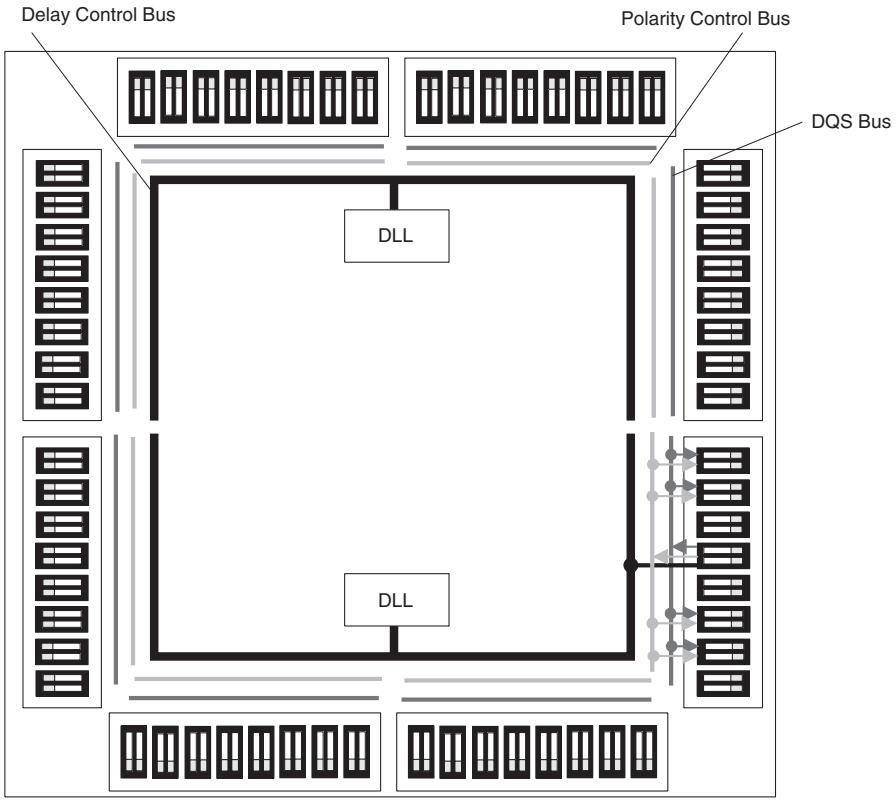


Figure 2-33. DLL Calibration Bus and DQS/DQS Transition Distribution



Oscillator

Every LatticeECP/EC device has an internal CMOS oscillator which is used to derive a master clock for configuration. The oscillator and the master clock run continuously. The default value of the master clock is 2.5MHz. Table 2-15 lists all the available Master Clock frequencies. When a different Master Clock is selected during the design process, the following sequence takes place:

1. User selects a different Master Clock frequency.
2. During configuration the device starts with the default (2.5MHz) Master Clock frequency.
3. The clock configuration settings are contained in the early configuration bit stream.
4. The Master Clock frequency changes to the selected frequency once the clock configuration bits are received.

For further information about the use of this oscillator for configuration, please see the list of technical documentation at the end of this data sheet.

Table 2-15. Selectable Master Clock (CCLK) Frequencies During Configuration

CCLK (MHz)	CCLK (MHz)	CCLK (MHz)
2.5*	13	45
4.3	15	51
5.4	20	55
6.9	26	60
8.1	30	130
9.2	34	—
10.0	41	—

Density Shifting

The LatticeECP/EC family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

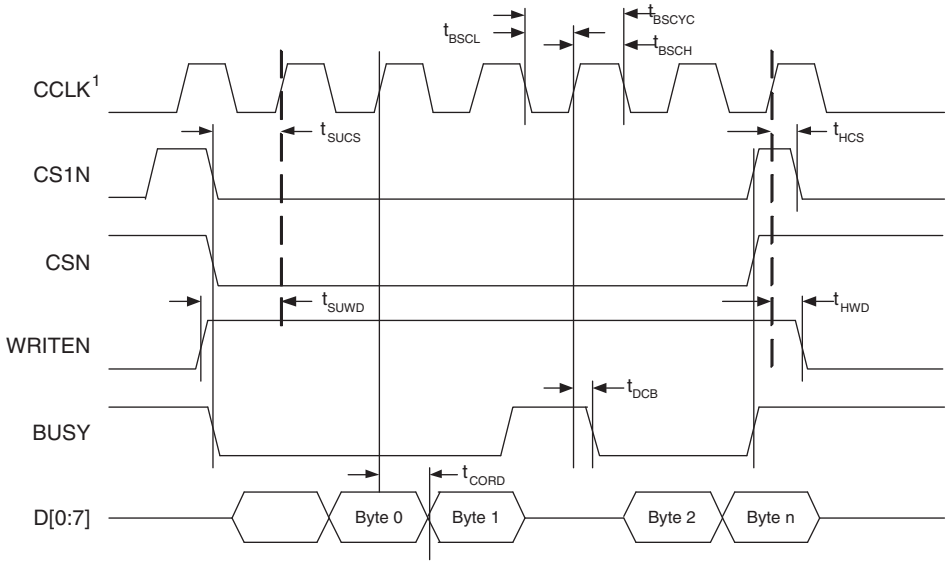
sysI/O Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

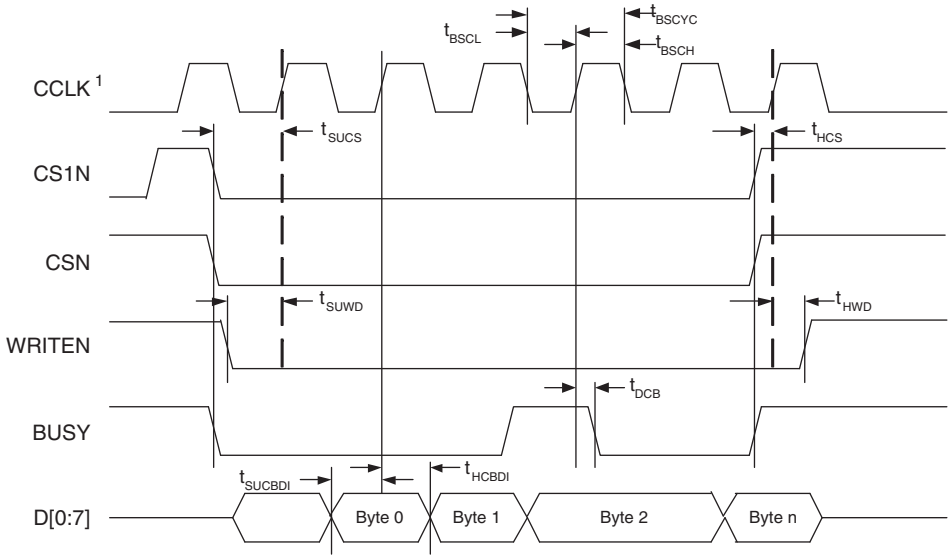
Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input voltage		0	—	2.4	V
V_{THD}	Differential input threshold		+/-100	—	—	mV
V_{CM}	Input common mode voltage	100mV ð V_{THD}	V_{THD}/2	1.2	1.8	V
		200mV ð V_{THD}	V_{THD}/2	1.2	1.9	V
		350mV ð V_{THD}	V_{THD}/2	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 Ohm	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 Ohm	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} + V_{OM})/2, R_T = 100 Ohm	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

Figure 3-12. sysCONFIG Parallel Port Read Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Figure 3-13. sysCONFIG Parallel Port Write Cycle



1. In Master Parallel Mode the FPGA provides CCLK. In Slave Parallel Mode the external device provides CCLK.

Pin Information Summary (Cont.)

Pin Type		LFECP/EC15		LFECP20/EC20		LFECP/EC33	
		256-fpBGA	484-fpBGA	484-fpBGA	672-fpBGA	484-fpBGA	672-fpBGA
Single Ended User I/O		195	352	360	400	360	496
Differential Pair User I/O		97	176	180	200	180	248
Configuration	Dedicated	13	13	13	13	13	13
	Muxed	56	56	56	56	56	56
TAP		5	5	5	5	5	5
Dedicated (total without supplies)		208	373	373	509	373	509
V_{CC}		10	20	20	32	16	28
V_{CCAUX}		2	12	12	20	12	20
V_{CCPLL}		0	0	0	0	4	4
V_{CCIO}	Bank0	2	4	4	6	4	6
	Bank1	2	4	4	6	4	6
	Bank2	2	4	4	6	4	6
	Bank3	2	4	4	6	4	6
	Bank4	2	4	4	6	4	6
	Bank5	2	4	4	6	4	6
	Bank6	2	4	4	6	4	6
	Bank7	2	4	4	6	4	6
GND, GND0-GND7		20	44	44	63	44	63
NC		0	11	3	96	3	0
Single Ended/ Differential I/O Pair per Bank	Bank0	32/16	48/24	48/24	64/32	48/24	64/32
	Bank1	18/9	48/24	48/24	48/24	48/24	64/32
	Bank2	16/8	40/20	40/20	40/20	40/20	56/28
	Bank3	32/16	40/20	44/22	48/24	44/22	64/32
	Bank4	17/8	48/24	48/24	48/24	48/24	64/32
	Bank5	32/16	48/24	48/24	64/32	48/24	64/32
	Bank6	32/16	40/20	44/22	48/24	44/22	64/32
	Bank7	16/8	40/20	40/20	40/20	40/20	56/28
V_{CCJ}		1	1	1	1	1	1

Note: During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.

LFEC1, LFEC3, LFECP/EC6 Logic Signal Connections: 144 TQFP

Pin Number	LFEC1				LFEC3				LFECP6/EC6			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
1	VCCIO7	7			VCCIO7	7			VCCIO7	7		
2	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7	PL2A	7	T	VREF2_7
3	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7	PL2B	7	C	VREF1_7
4	PL3A	7	T		PL7A	7	T		PL7A	7	T	
5	PL3B	7	C		PL7B	7	C		PL7B	7	C	
6	PL4A	7	T		PL8A	7	T		PL8A	7	T	
7	PL4B	7	C		PL8B	7	C		PL8B	7	C	
8	PL5A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0	PL9A	7	T	PCLKT7_0
9	PL5B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0	PL9B	7	C	PCLKC7_0
10	XRES	6			XRES	6			XRES	6		
11	NC	-			NC	-			VCC	-		
12	NC	-			NC	-			GND	-		
13	VCC	-			VCC	-			VCC	-		
14	TCK	6			TCK	6			TCK	6		
15	GND	-			GND	-			GND	-		
16	TDI	6			TDI	6			TDI	6		
17	TMS	6			TMS	6			TMS	6		
18	TDO	6			TDO	6			TDO	6		
19	VCCJ	6			VCCJ	6			VCCJ	6		
20	PL7A	6	T	LLM0_PLLT_IN_A	PL11A	6	T	LLM0_PLLT_IN_A	PL20A	6	T	LLM0_PLLT_IN_A
21	PL7B	6	C	LLM0_PLLC_IN_A	PL11B	6	C	LLM0_PLLC_IN_A	PL20B	6	C	LLM0_PLLC_IN_A
22	PL8A	6	T	LLM0_PLLT_FB_A	PL12A	6	T	LLM0_PLLT_FB_A	PL21A	6	T	LLM0_PLLT_FB_A
23	PL8B	6	C	LLM0_PLLC_FB_A	PL12B	6	C	LLM0_PLLC_FB_A	PL21B	6	C	LLM0_PLLC_FB_A
24	VCCIO6	6			VCCIO6	6			VCCIO6	6		
25	PL9A	6	T		PL13A	6	T		PL22A	6	T	
26	PL9B	6	C		PL13B	6	C		PL22B	6	C	
27	PL10A	6	T		PL14A	6	T		PL23A	6	T	
28	GND6	6			GND6	6			GND6	6		
29	PL10B	6	C		PL14B	6	C		PL23B	6	C	
30	PL11A	6	T	LDQS11	PL15A	6	T	LDQS15	PL24A	6	T	LDQS24
31	PL11B	6	C		PL15B	6	C		PL24B	6	C	
32	PL12A	6	T		PL16A	6	T		PL25A	6	T	
33	PL12B	6	C		PL16B	6	C		PL25B	6	C	
34	PL14A	6	T	VREF1_6	PL18A	6	T	VREF1_6	PL27A	6	T	VREF1_6
35	PL14B	6	C	VREF2_6	PL18B	6	C	VREF2_6	PL27B	6	C	VREF2_6
36	VCCIO6	6			VCCIO6	6			VCCIO6	6		
37*	GND5 GND6	-			GND5 GND6	-			GND5 GND6	-		
38	VCCIO5	5			VCCIO5	5			VCCIO5	5		
39	PB2A	5	T		PB10A	5	T		PB10A	5	T	
40	PB2B	5	C		PB10B	5	C		PB10B	5	C	
41	PB3A	5	T		PB11A	5	T		PB11A	5	T	
42	PB3B	5	C		PB11B	5	C		PB11B	5	C	
43	PB5B	5			PB13B	5			PB13B	5		
44	VCCIO5	5			VCCIO5	5			VCCIO5	5		
45	PB6A	5	T	BDQS6	PB14A	5	T	BDQS14	PB14A	5	T	BDQS14
46	PB6B	5	C		PB14B	5	C		PB14B	5	C	
47	PB7A	5	T		PB15A	5	T		PB15A	5	T	
48	PB7B	5	C		PB15B	5	C		PB15B	5	C	
49	PB8A	5	T	VREF2_5	PB16A	5	T	VREF2_5	PB16A	5	T	VREF2_5

LFECP/EC6, LFECP/EC10 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFECP6/LFEC6				LFECP10/LFEC10			
	Pin Function	Bank	LVDS	Dual Function	Pin Function	Bank	LVDS	Dual Function
127	CFG0	3			CFG0	3		
128	VCC	-			VCC	-		
129	PROGRAMN	3			PROGRAMN	3		
130	CCLK	3			CCLK	3		
131	INITN	3			INITN	3		
132	GND	-			GND	-		
133	DONE	3			DONE	3		
134	GND	-			GND	-		
135	VCC	-			VCC	-		
136	VCCAUX	-			VCCAUX	-		
137	PR9B	2	C	PCLKC2_0	PR18B	2	C	PCLKC2_0
138	GND2	2			GND2	2		
139	PR9A	2	T	PCLKT2_0	PR18A	2	T	PCLKT2_0
140	PR8B	2	C		PR17B	2	C	
141	PR8A	2	T		PR17A	2	T	
142	PR7B	2	C		PR16B	2	C	
143	PR7A	2	T		PR16A	2	T	
144	PR6B	2	C		PR15B	2	C	
145	VCCIO2	2			VCCIO2	2		
146	PR6A	2	T	RDQS6	PR15A	2	T	RDQS15
147	PR5B	2	C		PR14B	2	C	
148	PR5A	2	T		PR14A	2	T	
149	PR4B	2	C		PR13B	2	C	
150	PR4A	2	T		PR13A	2	T	
151	NC	-			GND	-		
152	NC	-			VCC	-		
153	PR2B	2	C	VREF1_2	PR2B	2	C	VREF1_2
154	PR2A	2	T	VREF2_2	PR2A	2	T	VREF2_2
155	VCCIO2	2			VCCIO2	2		
156*	GND1 GND2	-			GND1 GND2	-		
157	VCCIO1	1			VCCIO1	1		
158	PT33A	1			PT41A	1		
159	PT25B	1	C		PT33B	1	C	
160	PT25A	1	T		PT33A	1	T	
161	PT24B	1	C		PT32B	1	C	
162	PT24A	1	T		PT32A	1	T	
163	PT23B	1	C		PT31B	1	C	
164	PT23A	1	T		PT31A	1	T	
165	PT22B	1	C		PT30B	1	C	
166	PT22A	1	T	TDQS22	PT30A	1	T	TDQS30
167	PT21B	1	C		PT29B	1	C	
168	GND1	1			GND1	1		

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
C16	PR4B	2	C		PR4B	2	C	
B16	PR4A	2	T		PR4A	2	T	
C15	PR3B	2	C		PR3B	2	C	
C14	PR3A	2	T		PR3A	2	T	
D14	PR2B	2	C	VREF1_2	PR2B	2	C	VREF1_2
D13	PR2A	2	T	VREF2_2	PR2A	2	T	VREF2_2
GND	GND2	2			GND2	2		
GND	GND1	1			GND1	1		
-	-	-			GND1	1		
B13	NC	-			PT26B	1	C	
C13	NC	-			PT26A	1	T	
C12	PT25B	1	C		PT25B	1	C	
-	-	-			GND1	1		
D12	PT25A	1	T		PT25A	1	T	
A15	PT24B	1	C		PT24B	1	C	
B14	PT24A	1	T		PT24A	1	T	
D11	PT23B	1	C		PT23B	1	C	
C11	PT23A	1	T		PT23A	1	T	
E10	PT22B	1	C		PT22B	1	C	
E11	PT22A	1	T	TDQS22	PT22A	1	T	TDQS22
A14	PT21B	1	C		PT21B	1	C	
GND	GND1	1			GND1	1		
A13	PT21A	1	T		PT21A	1	T	
D10	PT20B	1	C		PT20B	1	C	
C10	PT20A	1	T		PT20A	1	T	
A12	PT19B	1	C	VREF2_1	PT19B	1	C	VREF2_1
B12	PT19A	1	T	VREF1_1	PT19A	1	T	VREF1_1
A11	PT18B	1	C		PT18B	1	C	
B11	PT18A	1	T		PT18A	1	T	
A10	PT17B	0	C	PCLKC0_0	PT17B	0	C	PCLKC0_0
GND	GND0	0			GND0	0		
B10	PT17A	0	T	PCLKT0_0	PT17A	0	T	PCLKT0_0
C9	PT16B	0	C	VREF1_0	PT16B	0	C	VREF1_0
B9	PT16A	0	T	VREF2_0	PT16A	0	T	VREF2_0
E9	PT15B	0	C		PT15B	0	C	
D9	PT15A	0	T		PT15A	0	T	
D8	PT14B	0	C		PT14B	0	C	
C8	PT14A	0	T	TDQS14	PT14A	0	T	TDQS14
A9	PT13B	0	C		PT13B	0	C	
GND	GND0	0			GND0	0		
A8	PT13A	0	T		PT13A	0	T	
B8	PT12B	0	C		PT12B	0	C	
B7	PT12A	0	T		PT12A	0	T	

LFEC3 and LFECP/EC6 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFEC3				LFECP6/LFEC6			
	Ball Function	Bank	LVDS	Dual Function	Ball Function	Bank	LVDS	Dual Function
E5	VCC	-			VCC	-		
E8	VCC	-			VCC	-		
M12	VCC	-			VCC	-		
M5	VCC	-			VCC	-		
M9	VCC	-			VCC	-		
B15	VCCAUX	-			VCCAUX	-		
R2	VCCAUX	-			VCCAUX	-		
F7	VCCIO0	0			VCCIO0	0		
F8	VCCIO0	0			VCCIO0	0		
F10	VCCIO1	1			VCCIO1	1		
F9	VCCIO1	1			VCCIO1	1		
G11	VCCIO2	2			VCCIO2	2		
H11	VCCIO2	2			VCCIO2	2		
J11	VCCIO3	3			VCCIO3	3		
K11	VCCIO3	3			VCCIO3	3		
L10	VCCIO4	4			VCCIO4	4		
L9	VCCIO4	4			VCCIO4	4		
L7	VCCIO5	5			VCCIO5	5		
L8	VCCIO5	5			VCCIO5	5		
J6	VCCIO6	6			VCCIO6	6		
K6	VCCIO6	6			VCCIO6	6		
G6	VCCIO7	7			VCCIO7	7		
H6	VCCIO7	7			VCCIO7	7		
F6	VCC	-			VCC	-		
F11	VCC	-			VCC	-		
L11	VCC	-			VCC	-		
L6	VCC	-			VCC	-		

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
P5	PL32B	6	C		P5	PL44B	6	C	
P6	PL33A	6	T		P6	PL45A	6	T	
R5	PL33B	6	C		R5	PL45B	6	C	
U1	PL34A	6	T		U1	PL46A	6	T	
U2	PL34B	6	C		U2	PL46B	6	C	
T3	PL35A	6	T		T3	PL47A	6	T	
GND	GND6	6			GND	GND6	6		
T4	PL35B	6	C		T4	PL47B	6	C	
R6	PL36A	6	T	LDQS36	R6	PL48A	6	T	LDQS48
T5	PL36B	6	C		T5	PL48B	6	C	
T6	PL37A	6	T		T6	PL49A	6	T	
U5	PL37B	6	C		U5	PL49B	6	C	
U3	PL38A	6	T		U3	PL50A	6	T	
U4	PL38B	6	C		U4	PL50B	6	C	
V1	PL39A	6	T		V1	PL51A	6	T	
GND	GND6	6			GND	GND6	6		
V2	PL39B	6	C		V2	PL51B	6	C	
U7	TCK	6			U7	TCK	6		
V4	TDI	6			V4	TDI	6		
V5	TMS	6			V5	TMS	6		
V3	TDO	6			V3	TDO	6		
U6	VCCJ	6			U6	VCCJ	6		
W1	PL41A	6	T	LLM0_PLLT_IN_A	W1	PL53A	6	T	LLM0_PLLT_IN_A
W2	PL41B	6	C	LLM0_PLLC_IN_A	W2	PL53B	6	C	LLM0_PLLC_IN_A
V6	PL42A	6	T	LLM0_PLLT_FB_A	V6	PL54A	6	T	LLM0_PLLT_FB_A
W6	PL42B	6	C	LLM0_PLLC_FB_A	W6	PL54B	6	C	LLM0_PLLC_FB_A
Y1	PL43A	6	T		Y1	PL55A	6	T	
Y2	PL43B	6	C		Y2	PL55B	6	C	
W3	PL44A	6	T		W3	PL56A	6	T	
GND	GND6	6			GND	GND6	6		
W4	PL44B	6	C		W4	PL56B	6	C	
AA1	PL45A	6	T	LDQS45	AA1	PL57A	6	T	LDQS57
AB1	PL45B	6	C		AB1	PL57B	6	C	
Y4	PL46A	6	T		Y4	PL58A	6	T	
Y3	PL46B	6	C		Y3	PL58B	6	C	
AC1	PL47A	6	T		AC1	PL59A	6	T	
AB2	PL47B	6	C		AB2	PL59B	6	C	
AA2	NC	-			AA2	PL60A	6	T	
-	-	-			GND	GND6	6		
AA3	NC	-			AA3	PL60B	6	C	
W5	NC	-			W5	PL61A	6	T	
Y5	NC	-			Y5	PL61B	6	C	

LFECP/EC20, LFECP/EC33 Logic Signal Connections: 672 fpBGA (Cont.)

LFEC20/LFECP20					LFECP/EC33				
Ball Number	Ball Function	Bank	LVDS	Dual Function	Ball Number	Ball Function	Bank	LVDS	Dual Function
U12	GND	-			U12	GND	-		
U13	GND	-			U13	GND	-		
U14	GND	-			U14	GND	-		
U15	GND	-			U15	GND	-		
U16	GND	-			U16	GND	-		
U17	GND	-			U17	GND	-		
H10	VCC	-			H10	VCC	-		
H11	VCC	-			H11	VCC	-		
H16	VCC	-			H16	VCC	-		
H17	VCC	-			H17	VCC	-		
H18	VCC	-			H18	VCC	-		
H19	VCC	-			H19	VCC	-		
H8	VCC	-			H8	VCC	-		
H9	VCC	-			H9	VCC	-		
J18	VCC	-			J18	VCC	-		
J9	VCC	-			J9	VCC	-		
K8	VCC	-			K8	VCC	-		
L19	VCC	-			L19	VCC	-		
M19	VCC	-			M19	VCC	-		
N7	VCC	-			N7	VCC	-		
R20	VCC	-			R20	VCC	-		
R7	VCC	-			R7	VCC	-		
T19	VCC	-			T19	VCC	-		
V18	VCC	-			V18	VCC	-		
V8	VCC	-			V8	VCC	-		
V9	VCC	-			V9	VCC	-		
W10	VCC	-			W10	VCC	-		
W11	VCC	-			W11	VCC	-		
W16	VCC	-			W16	VCC	-		
W17	VCC	-			W17	VCC	-		
W18	VCC	-			W18	VCC	-		
W19	VCC	-			W19	VCC	-		
W8	VCC	-			W8	VCC	-		
W9	VCC	-			W9	VCC	-		
H12	VCCIO0	0			H12	VCCIO0	0		
H13	VCCIO0	0			H13	VCCIO0	0		
J10	VCCIO0	0			J10	VCCIO0	0		
J11	VCCIO0	0			J11	VCCIO0	0		
J12	VCCIO0	0			J12	VCCIO0	0		
J13	VCCIO0	0			J13	VCCIO0	0		
H14	VCCIO1	1			H14	VCCIO1	1		
H15	VCCIO1	1			H15	VCCIO1	1		

LatticeECP/EC Family Data Sheet Revision History

Revision History

Date	Version	Section	Change Summary
June 2004	01.0	—	Initial release.
August 2004	01.1	Introduction	Added new device LFECP/LFEC33 in Table 1-1.
		Architecture	Added New device LFECP/LFEC33 in Tables 2-9, 2-10 and 2-11.
		DC & Switching Characteristics	Added New device LFECP/LFEC33 on Supply current (Standby) tables.
			Added New device LFECP/LFEC33 on Initialization Supply current tables.
		Ordering Information	Added 33K Logic Capacity Device in Part Number Description section.
			Added EC33, ECP33 device: Industrial and Commercial to Part Number table.
			Corrected I/O counts in the part number tables for 100/144 TQFP and 208 PQFP packages to match Table 1-1 on page 1.
November 2004	01.3	Introduction	Changed DDR333 (166MHz) to DDR400 (200MHz)
			Added “RSDS” offering to the Features list: Flexible I/O Buffer
		Architecture	Added information about Secondary Clock Sources
			Added information about DCS
			Added a section on “Recommended Power-up Sequence”
			Updated Figure 2-24 “DQS Routing”
			Added DSP Block performance numbers to Table 2-11
			Added another row for RSDS in Table 2-13 and Table 2-14
		DC & Switching Characteristics	Updated new timing numbers
			Added numbers to derating table
			Added DC conditions to RSDS table
			Changed LVDS Max. V_{CCIO} to 2.625
			Added a row for RSDS in “Operating Condition” table
			Updated standby and initialization current table
			Added figure 3-12: sysConfig SPI port sequence
			Added DDR Timing Table and DDR Timings Figure 3-6
		Pinout Information	Added LFECP/EC6 to Pin Information
			Added LFECP/EC6 to Power Supply and NC Connections
			Added LFECP/EC6 144 TQFP Logic Signal Connections
			Added LFECP/EC6 208 PQFP Logic Signal Connections
			Added LFECP/EC6 256 fpBGA Logic Signal Connections
			Added LFECP/EC6 484 fpBGA Logic Signal Connections
		Ordering Information	Added 33K Logic Capacity Device in Part Number Description section.
			Added Part Number table for Commercial EC33.
			Added Part Number table for Commercial ECP33.
			Added Part Number table for Industrial EC33.
			Added Part Number table for Industrial ECP33.

Date	Version	Section	Change Summary
December 2004	01.4	Architecture	Updated Hot Socketing Recommended Power Up Sequence section.
		Pinout Information	Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Pin Information
			Added LFEC1, LFEC3, LFECP/EC10, LFECP/EC15 to Power Supply and NC Connections
			Added LFEC1 and LFEC3 100 TQFP Pinout
			Added LFEC1 and LFEC3 144 TQFP Pinout
			Added LFEC1, LFEC3 and LFECP/EC10 208 PQFP Pinout
			Added LFEC3, LFECP/EC10 and LFECP/EC15 256 fpBGA Pinout
			Added LFECP/EC10 and LFECP/EC15 484 fpBGA Pinout
		Ordering Information	Added Lead-Free Package Designators
			Added Lead-Free Ordering Part Numbers
		Supplemental Information	Updated list of technical notes.
April 2005	01.5	Architecture	EBR memory support section has been updated with clarification.
			Updated sysIO buffer pair section.
		DC & Switching Characteristics	Hot Socketing Specification has been updated.
			DC Electrical Characteristics table (I_{IL}, I_{IH}) has been updated.
			Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			External Switching Characteristics section has been updated.
			Removed t_{RSTW} spec. from PLL Parameter table.
			t_{RST} specifications have been updated.
			sysCONFIG Port Timing Specifications (t_{BSCL}, t_{IODISS}, t_{PRGMRJ}) have been updated.
		Pinout Information	Added LFECP/EC33 Pinout Information
			Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
			484-fpBGA logic connection has been updated (Ball # J6, J17, P6 and P17 for ECP/EC33 are now called VCCPLL).
			672-fpBGA logic connection has been updated (Ball # K19, L8, U19, U8 for ECP/EC33 are now called VCCPLL).
May 2005	01.6	Introduction	ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.
		Architecture	Table 2-10 has been updated (ECP/EC33 EBR SRAM Bits and Blocks have been updated to 498K and 54 respectively.)
			Recommended Power Up Sequence section has been removed.
		DC & Switching Characteristics	Supply Current (Standby) table has been updated.
			Initialization Supply Current table has been updated.
			Vos test condition has been updated to (VOP+VOM)/2.
			Register-to-Register performance table has been updated (rev. G 0.27).
			External switching characteristics have been updated (rev. G 0.27).
			Internal timing parameters have been updated (rev. G 0.27).
			Timing adders have been updated (rev. G 0.27).
			sysCONFIG port timing specifications have been updated.
		Pinout Information	Pin Information Summary table has been updated.
			Power Supply and NC Connection table has been updated.
		Ordering Information	OPN list has been updated.